



Q. Metrology, Inspection, and Yield Enhancement 분과

2019년 2월 15일(금), 11:00-12:30

Room K (국실, 5층)

[FK2-Q] Metrology, Inspection, and Yield Enhancement

좌장: 조용재 책임연구원(KRISS), 김진승 교수(전북대학교)

<p>FK2-Q-1 11:00-11:15</p>	<p><b>Discrete Scanning Based TSOM Image Generation and Measurement</b> Youngback Kim, Junhee Jeong, and Joonghwee Cho <i>Department of Embedded Systems Engineering, Incheon National University</i></p>
<p>FK2-Q-2 11:15-11:45</p>	<p>[초청] <b>Automated Inline AFM Solutions for Semiconductor Industry</b> Sang-Joon Cho<sup>1</sup>, Byung-Woon Ahn<sup>1</sup>, Tae-Gon Kim<sup>2,3</sup>, and Sang-il Park<sup>1</sup> <i><sup>1</sup>Park Systems Corp, <sup>2</sup>Department of Materials Science and Chemical Engineering, Hanyang University ERICA, <sup>3</sup>Imec vzw, Leuven, Belgium</i></p>
<p>FK2-Q-3 11:45-12:00</p>	<p><b>The Enhancement to Estimate the Yield Impact of Unknown Defects in the Advanced Technology Node Using Volume Diagnostics</b> Jeongsu Park, Seungjin Yang, and Brad Kim <i>Synopsys Korea</i></p>
<p>FK2-Q-4 12:00-12:15</p>	<p><b>A Study on a Near-Field Microscope with Dark-Field Illumination to Detect Defects on Semiconductor Wafer</b> Woojun Han<sup>1</sup>, Hankyung Oh<sup>1</sup>, Jaisoon Kim<sup>1</sup>, and Yoonki Lee<sup>2</sup> <i><sup>1</sup>Department of Physics, Myongji University, <sup>2</sup>AUROS Technology</i></p>
<p>FK2-Q-5 12:15-12:30</p>	<p><b>Critical Nanotopography Metrology Study for Good CMP Process Control and Electrical Bonding Yield in Wafer-To-Wafer Hybrid Bonding</b> Tae-Gon Kim<sup>1,2</sup>, Soon-Wook Kim<sup>1</sup>, Heon-Yul Ryu<sup>2</sup>, Nancy Heylen<sup>1</sup>, Ferenc Fodor<sup>1</sup>, Dimitrios Velenis<sup>1</sup>, Tom Vandeweyer<sup>1</sup>, Sang-Joon Cho<sup>1</sup>, Sang-il Park<sup>1</sup>, Jin-Goo Park<sup>2</sup>, and Eric Beyne<sup>1</sup> <i><sup>1</sup>Imec vzw, Belgium, <sup>2</sup>Department of Materials Science and Chemical Engineering, Hanyang University ERICA, <sup>3</sup>Park Systems</i></p>